In the Claims

Claims 1-13 are canceled.

14. [Currently Amended] An article of manufacture comprising:

an electronic device wafer processing intermediate member adapted to receive an electronic device wafer having an electrical coupling and couple with a chuck having an electrical coupling, the intermediate member comprising:

an electrical interconnect configured to electrically connect the electrical coupling of the electronic device wafer with the electrical coupling of the chuck;

wherein the intermediate member is configured to support the electronic device wafer comprising a plurality of integrated circuit dies being fabricated.

15. [Currently Amended] The article according to claim 14 wherein the intermediate member includes a plurality of electrical interconnects configured to electrically connect a plurality of electrical couplings of ~~an~~ the electronic device wafer and a chuck.

16. [Previously Presented] The article according to claim 14 wherein the electrical interconnect comprises a pogo pin.

17. [Previously Presented] The article according to claim 14 wherein the electrical interconnect comprises a wire.

Claims 18-52 are canceled.

53. [Previously Presented] The article according to claim 14 wherein the intermediate member comprises a substantially electrically nonconductive material.

54. [Currently Amended] A wafer processing apparatus comprising:

an electronic device wafer comprising a sensor and an electrical coupling in electrical communication with the sensor; and

an intermediate member comprising:

a first surface configured to support substantially an entirety of ~~an~~ the electronic device wafer;

a first electrical coupling adjacent to the first surface and configured to electrically connect with ~~an~~ the electrical coupling of the electronic device wafer;

a second surface opposite to the first surface;

a second electrical coupling adjacent to the second surface and configured to electrically connect with an electrical coupling of a chuck of the wafer processing apparatus; and

an electrical interconnect configured to electrically connect the first electrical

coupling with the second electrical coupling and to communicate electrical signals between the first electrical coupling and the second electrical coupling; and

wherein the sensor is in electrical communication with the first electrical coupling, the second electrical coupling and the electrical interconnect.

55. Cancel.

56. [Currently Amended] The apparatus of claim ~~55~~ 54 wherein the wafer has a surface, and an outwardly exposed surface of the electrical coupling of the wafer is substantially coplanar with the surface of the wafer.

57. [Previously Presented] The apparatus of claim 54 wherein the intermediate member comprises a substantially electrically nonconductive material.

58. [Previously Presented] The apparatus of claim 54 wherein the intermediate member includes a plurality of electrical interconnects configured to electrically connect a plurality of electrical couplings of the wafer and the chuck.

59. [Previously Presented] The apparatus of claim 54 wherein the electrical interconnect comprises a pogo pin.

60. [Previously Presented] The apparatus of claim 54 wherein the electrical interconnect comprises a wire.

61. [Previously Presented] A wafer processing apparatus comprising:

an intermediate member comprising an electrical interconnect configured to electrically connect an electrical coupling of an electronic device wafer with an electrical coupling of a chuck of the wafer processing apparatus, and wherein the electrical interconnect is configured to communicate electrical signals intermediate the electrical coupling of the wafer and the electrical coupling of the chuck.

62. [Previously Amended] The apparatus of claim 61 further comprising the electronic device wafer comprising an electrical coupling configured to electrically connect with the electrical interconnect of the intermediate member.

63. [Previously Presented] The apparatus of claim 62 wherein the wafer has a surface, and an outwardly exposed surface of the electrical coupling of the wafer is substantially coplanar with the surface of the wafer.

64. [Previously Presented] The apparatus of claim 61 wherein the intermediate member comprises a substantially electrically nonconductive material.

65. [Previously Presented] The apparatus of claim 61 wherein the intermediate member includes a plurality of electrical interconnects configured to electrically connect a plurality of electrical couplings of the wafer and the chuck.

66. [Previously Presented] The apparatus of claim 61 wherein the electrical interconnect comprises a pogo pin.

67. [Previously Presented] The apparatus of claim 61 wherein the electrical interconnect comprises a wire.

68. Cancel.

69. Cancel.

70. [Currently Amended] The apparatus of claim 54 wherein the intermediate member is configured to expose ~~a~~ the wafer to a processing environment within the wafer processing apparatus to form a plurality of discrete integrated circuits of a plurality of respective dies to be singulated from the wafer at a subsequent moment in time.

71. [Currently Amended] The apparatus of claim 54 further comprising a processing area configured to process ~~a~~ the wafer supported using the intermediate member to fabricate a plurality of discrete integrated circuits of a plurality of respective dies to be singulated from the wafer at a subsequent moment in time.

72. [Currently Amended] The apparatus of claim 54 wherein the wafer processing apparatus is configured to process ~~a~~ the wafer supported using the intermediate member to fabricate a plurality of discrete integrated circuits of a plurality of respective dies to be singulated from the wafer at a subsequent moment in time.

73. [Previously Presented] The apparatus of claim 54 wherein the wafer comprises a semiconductive wafer.

74. [Currently Amended] The apparatus of claim ~~55~~ 54 wherein the electronic device wafer comprises a plurality of integrated circuit dies prior to singulation of at least one of the dies at a subsequent moment in time.

75. [Previously Presented] The apparatus of claim 61 wherein the intermediate member is configured to support a wafer for processing within the wafer processing apparatus to form a plurality of discrete integrated circuits of a plurality of respective dies to be singulated from the wafer at a subsequent moment in time.

76. [Previously Presented] The apparatus of claim 61 wherein the intermediate member is configured to expose a wafer to a processing environment within the wafer processing apparatus to form a plurality of discrete integrated circuits of a plurality of respective dies to be singulated from the wafer at a subsequent moment in time.

77. [Previously Presented] The apparatus of claim 61 further comprising a processing area configured to process a wafer supported using the intermediate member to fabricate a plurality of discrete integrated circuits of a plurality of respective dies to be singulated from the wafer at a subsequent moment in time.

78. [Previously Presented] The apparatus of claim 61 wherein the wafer processing apparatus is configured to process a wafer supported using the intermediate member to fabricate a plurality of discrete integrated circuits of a plurality of respective dies to be singulated from the wafer at a subsequent moment in time.

79. [Previously Presented] The apparatus of claim 61 wherein the wafer comprises a semiconductive wafer.

80. [Previously Presented] The apparatus of claim 62 wherein the electronic device wafer comprises a plurality of integrated circuit dies prior to singulation of at least one of the dies at a subsequent moment in time.